



Solder wire IF 1000M

INTERFLUX®
ELECTRONICS N.V.



Technical data IF 1000M

Ver: 3.11 27-10-15

Page 1



Lead-free, rosin based, activated no-clean solder wire

Description:

Interflux® **IF 1000M** is a no-clean solder wire that has been developed to give increased wetting on surfaces that are difficult to solder, e.g. OSP, Ni, Zn, messing, German silver,... as well as on degraded and oxidised surfaces.

The solder wire contains halogens and is classified as RO L1 according to IPC and EN-standards.

The solder wire contains a colophony based body that has been designed to enhance spreading of the solder on solderable surfaces.

IF 1000M is useable in both hand soldering and automated soldering processes.

Depending on the temperature settings, residues can vary from transparent to amber.



Products pictured may differ from the product delivered

More information:

Work instructions	2
Handling	2
Test results	3
Packaging	4

Key advantages:

- Increased wetting properties on surfaces that are difficult to solder.
- Suitable for automated soldering
- RO L1

Availability

Flux type: IF 1000M
Flux content: 2,2 — 3,5% w/w

alloy	melting point	diameters					
		0,35	0,50	0,70	1,00	1,50	2,00
Sn96,5Ag3Cu0,5	217-219°C	●	●	●	●	●	●
Sn99Ag0,3Cu0,7	217-227°C	●	●	●	●	●	●
Sn99,3Cu0,7	227°C	●	●	●	●	●	●

● = available ● = upon request



Work instructions

Manual soldering

The advised working temperature is between 360°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough pow-

er for your application.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered.

Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be

soldered meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. This will reduce the risk on flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety data-sheet of the product.



Test results

conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	RO L1	J-STD-004A
	F-SW 26	DIN 8511
	1.1.2	ISO 9454
qualitative copper mirror	passed	J-STD-004A IPC-TM-650 2.3.32
% halide content	< 0,5%	
acid value	210 ±30 mg KOH/g	J-STD-004A 2.3.13
visual	pass	J-STD-004 Ref. paragraph 3.5.4
Environmental		
		J-STD-004 IPC-TM-650 2.6.3.3
qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15
electro chemical migration	pass	J-STD-004A IPC-TM-650 2.6.14.1



Packaging

Spools of 100g, 500g and 1000g



Trade name: IF 1000M Lead-Free, Rosin Based, Activated No-Clean Solder Wire

D i s c l a i m e r

Because Interflux® Electronics N.V. cannot anticipate or control the many different conditions under which this information and our products may be used, we do not guarantee the applicability or the accuracy of this information or the suitability of our products in any given situation. Users of our products should make their own test to determine the suitability of each such product for their particular purposes. The product discussed is sold without such warranty, either express or implied.

Copyright:

INTERFLUX® ELECTRONICS

Please consult the latest
version of this document
on:

www.interflux.com

This document in another
language?:

www.interflux.com